									REVISI	ONS										
LTR	DESCRIPTION									DA	ATE (YI	R-MO-I	DA)		APPF	ROVED)			
A	Char 2435	nge boi 55. Edi	lerplate torial ch	to add nanges t	device throug	e class hout.	V. Ado	l case (outline	H for ve	endor C	CAGE		97-0	5-30			R. MC	NNIN	
В	Made change to footnote $\underline{1}$ / in table IIA. Update boilerplaterrp								01-12-20				R. MONNIN							
С	Char	nae tes	t svmbo	ol "los"	to "lıc	" in ta	ble IIB.	-rrp						03-05-20 R. MONNIN			NNIN			
		ige tes	<u>t Symbo</u>	<u>105</u>		ווו נמ		<u>rtp</u>												
REV																				
SHEET																				
REV																				
SHEET																				
REV STATUS				REV			С	С	С	С	С	С	С	С	С	С	С			
OF SHEETS				SHE			1	2	3	4	5	6	7	8	9	10	11			
STANDARD CHI MICROCIRCUIT			PREPARED BY Rajesh Pithadia CHECKED BY Rajesh Pithadia					DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216 http://www.dscc.dla.mil												
DRAWING THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE			≣	APPROVED BY Raymond Monnin DRAWING APPROVAL DATE 88-10-17					MICROCIRCUIT, LINEAR, LOW-NOISE, PRECISION, HIGH SPEED OPERATIONAL AMPLIFIER, MONOLITHIC SILICON											
AMSC N/A			REVIS	SION I	LEVEL	С			,	ZE		GE CC 67268			ł	5962-	-8853	57		
			SHEET 1 OF 11																	

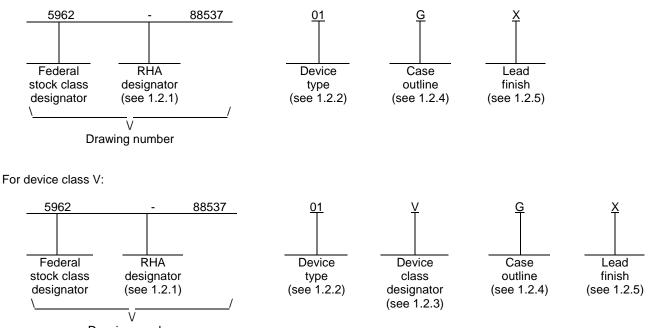
DSCC FORM 2233 APR 97 <u>DISTRIBUTION STATEMENT A</u>. Approved for public release; distribution is unlimited.

1. SCOPE

1.1 <u>Scope</u>. This drawing documents two product assurance class levels consisting of high reliability (device classes Q and M) and space application (device class V). A choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels are reflected in the PIN.

1.2 <u>PIN</u>. The PIN is as shown in the following examples.

For device classes M and Q:



Drawing number

1.2.1 <u>RHA designator</u>. Device classes Q and V RHA marked devices meet the MIL-PRF-38535 specified RHA levels and are marked with the appropriate RHA designator. Device class M RHA marked devices meet the MIL-PRF-38535, appendix A specified RHA levels and are marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.

1.2.2 <u>Device type(s)</u>. The device type(s) identify the circuit function as follows:

Device type	<u>Generic number</u>	Circuit function
01	OP-37A	Low-noise, precision, high-speed operational amplifier
02	OP-37B	Low-noise, precision, high-speed operational amplifier
03	OP-37C	Low-noise, precision, high-speed operational amplifier

1.2.3 <u>Device class designator</u>. The device class designator is a single letter identifying the product assurance level as listed below. Since the device class designator has been added after the original issuance of this drawing, device classes M and Q designators will not be included in the PIN and will not be marked on the device.

Device class		Device requirem	ents documentation						
М		Vendor self-certification to the requirements for MIL-STD-883 compliant, non- JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A							
Q or V	Certification a	Certification and qualification to MIL-PRF-38535							
STANDARI MICROCIRCUIT D	-	SIZE A		5962-88537					
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C FORM 2234									

1.2.4 <u>Case outline(s)</u>. The case outline(s) are as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
G H P	MACY1-X8 GDFP1-F10 or CDFP2-F10 GDIP1-T8 or CDIP2-T8	8 10 8	Can Flat pack Dual-in-line
2	CQCC1-N20	20	Square leadless chip carrier

1.2.5 Lead finish. The lead finish is as specified in MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

1.3 Absolute maximum ratings. 1/

Supply voltage (V _S) Internal power dissipation <u>2</u> / Input voltage <u>3</u> / Output short-circuit duration	500 mW
Differential input voltage <u>4</u> /	
Differential input current $\frac{4}{}$ Storage temperature range Operating temperature range Lead temperature (soldering, 60 seconds) Junction temperature range (T _J)	-65°C to +150°C -55°C to +125°C +300°C
Thermal resistance, junction-to-case (θ_{JC})	See MIL-STD-1835
Thermal resistance, junction-to-ambient (θ _{JA}): Cases G and H Case P Case 2	150°C/W 119°C/W 110°C/W

1.4 Recommended operating conditions.

Supply voltage (V _S)	±15 V
Source resistor (R _S)	50 Ω
Ambient operating temperature range (T _A)	-55°C to +125°C

2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and handbooks</u>. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DoDISS) and supplement thereto, cited in the solicitation.

SPECIFICATION

DEPARTMENT OF DEFENSE

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

1/ Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.

2/ Must withstand the added PD due to short circuit test, e.g., IOS.

 $\frac{3}{2}$ For supply voltages less than ± 22 V, the absolute maximum input voltage is equal to the supply voltages.

4/ The device inputs are protected by back-to-back diodes. Current limiting resistors are not used in order to achieve low noise. If differential input voltage exceeds ±0.7 V, the input current should be limited to 25 mA.

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STANDARDS

DEPARTMENT OF DEFENSE

MIL-STD-883	-	Test Method Standard Microcircuits.
MIL-STD-1835	-	Interface Standard Electronic Component Case Outlines.

HANDBOOKS

DEPARTMENT OF DEFENSE

MIL-HDBK-103 -	List of Standard Microcircuit Drawings.
MIL-HDBK-780 -	Standard Microcircuit Drawings.

(Unless otherwise indicated, copies of the specification, standards, and handbooks are available from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 <u>Item requirements</u>. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. The individual item requirements for device class M shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein.

3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes Q and V or MIL-PRF-38535, appendix A and herein for device class M.

3.2.1 <u>Case outline(s)</u>. The case outline(s) shall be in accordance with 1.2.4 herein.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.

3.3 <u>Electrical performance characteristics and postirradiation parameter limits</u>. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.

3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table IIA. The electrical tests for each subgroup are defined in table I.

3.5 <u>Marking</u>. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-HDBK-103. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes Q and V shall be in accordance with MIL-PRF-38535. Marking for device class M shall be in accordance with MIL-PRF-38535, appendix A.

3.5.1 <u>Certification/compliance mark</u>. The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535. The compliance mark for device class M shall be a "C" as required in MIL-PRF-38535, appendix A.

3.6 <u>Certificate of compliance</u>. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6.2 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and herein or for device class M, the requirements of MIL-PRF-38535, appendix A and herein.

3.7 <u>Certificate of conformance</u>. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 or for device class M in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.

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	17	ABLE I. Electrical per	formance	e charactei	ristics.				
		Conditions <u>1</u> -55°C \leq T _A \leq +12							
Test	Test Symbol		25°C ecified	Group subgrou		evice type	Lir	nits	Unit
							Min	Max	
Input offset current	lio			1		01		35	nA
				2,3		-		50	
				1		02		50	
				2,3				85	
				1		03		75	
				2,3				135	-
Average input bias current	Ι _Β			1		01		±40	nA
				2,3				±60	-
				1		02		±55	
				2,3		-		±95	
				1		03		±80	
				2,3		Ī		±150	
Common mode rejection ratio	CMRR	$V_{CM} = IVR = \pm 11 V$	<u>2</u> /	1		01	114		dB
		$V_{CM} = IVR = \pm 10 V$	<u>2</u> /	2,3		-	108		
		$V_{CM} = IVR = \pm 11 V$	<u>2</u> /	1		02	106		-
		$V_{CM} = IVR = \pm 10 V$	<u>2</u> /	2,3			100		
		$V_{CM} = IVR = \pm 11 V$	<u>2</u> /	1		03	100		
		$V_{CM} = IVR = \pm 10 V$	<u>2</u> /	2,3			94		
Power supply rejection ratio	PSRR	$V_{S} = \pm 4.5 \text{ V to } \pm 18 \text{ V}$	V	1		01		10	μV/V
				2,3				16	_
				1		02		10	
				2,3				20	
				1		03		20	
				2,3				51	
See footnotes at end of table									
MICROCIRC				ZE A				596	2-88537
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	TABLE	I. Electrical performan	ice chara	cteristics -	- Continued.			
Test	Symbol	Conditions <u>1</u> -55°C \leq T _A \leq +12	25°C	Group		Lir	nits	Unit
		unless otherwise spe	ecified	subgrou	ps type	Min	Max	-
Large signal voltage gain	A _{VO}	$V_0 = \pm 10 \text{ V}, \text{ R}_L \ge 2$	kΩ	1	01	1000	Max	V/mV
gan				2,3		600		-
				1	02	1000		-
				2,3		500		-
				1	03	700		
				2,3		300		-
Output voltage swing	Vo	$R_L \ge 2 \ k\Omega$		1	01	±12		V
				2,3		±11.5		
				1	02	±12		
				2,3		±11		-
				1	03	±11.5		
				2,3		±10.5		
Power dissipation	PD	No load, $T_A = +25^{\circ}C$, ,	1	01,02		140	mW
					03		170	
Offset voltage adjustment range	Vosadj	$R_{P} = 10 \text{ k}\Omega, \underline{3}/$ $T_{A} = +25^{\circ}\text{C}$		1	All	±0.5		mV
Supply current	IS	No load, $T_A = +25^{\circ}C$;	1	01,02		4.67	mA
					03		5.67	-
Output short-circuit current	I _{OS+}	T _A = +25°C		1	All		80	mA
	I _{OS-}					-80		
Input offset voltage	V _{IO}			4	01		25	μV
				5,6			60	
				4	02		60	_
				5,6			200	
				4	03		100	-
See footnotes at end of table				5,6			300	
STANDARD MICROCIRCUIT DRAWING				ZE A			596	2-88537
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TABLE I. Electrical performance characteristics – Continued.							
Test	Symbol	$\begin{array}{l} Conditions \ \underline{1}/\\ -55^{\circ}C \leq T_A \leq +125^{\circ}C\\ \text{unless otherwise specified} \end{array}$	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Slew rate	SR	$V_{O} = \pm 7.5 \text{ V}, \text{ R}_{L} = 2 \text{ k}\Omega,$	7	All	11		V/µs
		C _L = 50 pF, T _A = +25°C					
Average input offset voltage drift	TCV _{OS}	Unnulled <u>4</u> /	8	01		0.6	μV/°C
-		T _A = -55°C, +125°C		02		1.3	
				03		1.8	1

<u>1</u>/ $V_S = \pm 15 \text{ V}, \text{ R}_S = 50 \Omega$, unless otherwise specified.

2/ IVR is defined as the V_{CM} range used for the CMRR test.

3/ R_P is a trim potentiometer used for adjustment of V_{OS}.

4/ TCV_{OS} is guaranteed, if not tested, to the limits specified.

3.8 <u>Notification of change for device class M</u>. For device class M, notification to DSCC-VA of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change as defined in MIL-PRF-38535, appendix A.

3.9 <u>Verification and review for device class M</u>. For device class M, DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

3.10 <u>Microcircuit group assignment for device class M</u>. Device class M devices covered by this drawing shall be in microcircuit group number 49 (see MIL-PRF-38535, appendix A).

4. QUALITY ASSURANCE PROVISIONS

4.1 <u>Sampling and inspection</u>. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. For device class M, sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.

4.2 <u>Screening</u>. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection.

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ase outlines	G, P	Н	2
Terminal number		Terminal symbo	<u> </u>
1	V _{OS} Trm	NC	NC
2	-IN	NULL	V _{OS} Trm
3	+IN	-IN	NC
4	V _{S-}	+IN	NC
5	NC	V _{S-}	-IN
6	OUT	NC	NC
7	V _{S+}	OUT	+IN
8	V _{OS} Trm	V _{S+}	NC
9		NULL	NC
10		NC	V _{S-}
11			NC
12			NC
13			NC
14			NC
15			OUT
16			NC
17			V _{S+}
18			NC
19			NC
20			V _{OS} Trm
C = No connecti			

FIGURE 1. Terminal connections.

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4.2.1 Additional criteria for device class M.

- a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015.
 - (2) $T_A = +125^{\circ}C$, minimum.
- b. Interim and final electrical test parameters shall be as specified in table IIA herein.
- 4.2.2 Additional criteria for device classes Q and V.
 - a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
 - b. Interim and final electrical test parameters shall be as specified in table IIA herein.
 - c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.

4.3 <u>Qualification inspection for device classes Q and V</u>. Qualification inspection for device classes Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4 <u>Conformance inspection</u>. Technology conformance inspection for classes Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections and as specified. Quality conformance inspection for device class M shall be in accordance with MIL-PRF-38535, appendix A and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4.1 Group A inspection.

- a. Tests shall be as specified in table IIA herein.
- b. Subgroups 9, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.

4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:

- a. Test condition A, B, C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
- b. $T_A = +125^{\circ}C$, minimum.
- c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

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Test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)	(in accord	roups lance with 535, table III)
	Device class M	Device class Q	Device class V
Interim electrical parameters (see 4.2)	1	1	1
Final electrical parameters (see 4.2)	1,2,3,4,5,6 <u>1</u> /	1,2,3,4,5,6 <u>1</u> /	1,2,3, <u>1/ 2</u> / 4,5,6
Group A test requirements (see 4.4)	1,2,3,4,5,6,7,8	1,2,3,4,5,6,7,8	1,2,3,4,5,6, 7,8
Group C end-point electrical parameters (see 4.4)	1	1	1 <u>2</u> /
Group D end-point electrical parameters (see 4.4)	1	1	1
Group E end-point electrical parameters (see 4.4)			

TABLE IIA. Electrical test requirements.

<u>1</u>/ PDA applies to subgroup 1. Exclude deltas from PDA.

2/ Delta limits as specified in table IIB shall be required where specified, and the delta limits shall be computed with reference to the previous interim electrical parameters.

TABLE IIB.	240 hour burn-in and group	C end-point electrical	oarameters.

Test	Lir	nit	De	elta	Unit
	Min	Max	Min	Max	
Vos		100		75	μV
IB		40		8	nA
I _{IO}		35		7	nA

4.4.2.2 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.

4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.4 <u>Group E inspection</u>. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein).

- a. End-point electrical parameters shall be as specified in table IIA herein.
- b. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535 for the RHA level being tested. For device class M, the devices shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535, appendix A for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at $T_A = +25^{\circ}C \pm 5^{\circ}C$, after exposure, to the subgroups specified in table IIA herein.
- c. When specified in the purchase order or contract, a copy of the RHA delta limits shall be supplied.

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5. PACKAGING

5.1 <u>Packaging requirements</u>. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

6. NOTES

6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.1.1 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractorprepared specification or drawing.

6.2 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

6.3 <u>Record of users</u>. Military and industrial users should inform Defense Supply Center Columbus when a system application requires configuration control and which SMD's are applicable to that system. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0544.

6.4 <u>Comments</u>. Comments on this drawing should be directed to DSCC-VA, Columbus, Ohio 43216-5000, or telephone (614) 692-0547.

6.5 <u>Abbreviations, symbols, and definitions</u>. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.

6.6 Sources of supply.

6.6.1 <u>Sources of supply for device classes Q and V</u>. Sources of supply for device classes Q and V are listed in QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DSCC-VA and have agreed to this drawing.

6.6.2 <u>Approved sources of supply for device class M</u>. Approved sources of supply for class M are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DSCC-VA.

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STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 03-05-20

Approved sources of supply for SMD 5962-88537 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535.

Standard	Vendor	Vendor	Reference military
microcircuit drawing	CAGE	similar	specification PIN
PIN <u>1</u> /	number	PIN <u>2</u> /	
5962-8853701VGA	24355	OP37AJ/QMLV	
5962-8853701GA	<u>3</u> /	OP-37AT/883B	M38510/13505BGX
	<u>3</u> /	OP-37AJ/883	
	<u>3</u> /	OP-37AH/883	
5962-8853701GC	<u>3</u> /	OP-37AT/883B	M38510/13505BGX
5962-8853701VPA	24355	OP37AZ/QMLV	
5962-8853701PA	<u>3</u> /	OP-37AD/883B	M38510/13505BPX
	3/	OP-37AZ/883	
	3/	OP-37AJ8/883	
5962-8853701V2A	24355	OP37ARC/QMLV	
5962-8853701VHA	24355	OP37AL/QMLV	
0002 0000101111	21000		
5962-88537012A	<u>3</u> /	OP-37AL/883	M38510/13505B2X
	<u>o</u> ,		
5962-88537022A	<u>3</u> /	OP-37BRC/883	M38510/13505B2X
0002 00001 022/1	<u>o</u> ,		
5962-8853702GA	3/	OP-37BT/883B	M38510/13505BGX
0002 00001 02011	<u>0</u> / 24355	OP-37BJ/883	
5962-8853702GC	<u>3/</u>	OP-37BT/883B	M38510/13505BGX
0002-00007 02GC	<u></u>	01-0101/0000	101000 TU/ T0000DGA
	2/		
5962-8853702PA	<u>3</u> /	OP-37BD/883B	M38510/13505BPX
	24355	OP-37BZ/883	1

See footnotes at end of table.

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.

STANDARD MICROCIRCUIT DRAWING BULLETIN - CONTINUED

Standard microcircuit drawing PIN <u>1</u> /	Vendor CAGE number	Vendor similar PIN <u>2</u> /	Reference military specification PIN
5962-8853703GA	<u>3</u> / <u>3</u> / <u>3</u> /	OP-37CT/883B OP-37CJ/883 OP-37CH/883	M38510/13505BGX
5962-8853703GC	<u>3</u> /	OP-37CT/883B	M38510/13505BGX
5962-8853703PA	<u>3</u> / <u>3</u> /	OP-37CD/883B OP-37CJ8/883	M38510/13505BPX
5962-88537032A	<u>3</u> /	OP-37CL/883	M38510/13505B2X

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- <u>2</u>/ <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
 2/ Not evaluable from an approved source of source).
- $\underline{3}$ / Not available from an approved source of supply.

Vendor CAGE <u>number</u> Vendor name and address

24355

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